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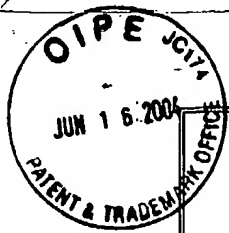
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INFORMATION DISCLOSURE  
CITATION IN AN  
APPLICATION

(PTO-1449)

ATTY. DOCKET NO.  
7720/FPS/MMCS/APCSERIAL NO.  
10/632,107APPLICANT  
Alexander T. SCHWARM et al.FILING DATE  
August 1, 2003GROUP  
2812

## U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
Q	5,497,381	03/05/96	O'Donoghue et al.			06/01/95
	5,761,065	06/02/98	Kittler et al.			03/30/95
	6,161,054 B1	12/12/00	Rosenthal et al.			09/17/98
	6,248,602 B1	06/19/01	Bode et al.			11/01/99
	6,346,426 B1	02/12/02	Toprac et al.			11/17/00
	6,368,883 B1	04/09/02	Bode et al.			08/10/99
	6,368,884 B1	04/09/02	Goodwin et al.			04/13/00
	6,405,096 B1	06/11/02	Toprac et al.			08/10/99
	2002/0107599 A1	08/08/02	Patel et al.			01/25/01

## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

Q	Yeh, C. Eugene, John C. Cheng, and Kwan Wong. 1993. "Implementation Challenges of a Feedback Control System for Wafer Fabrication." <i>IEEE/CHMT International Electronics Manufacturing Technology Symposium</i> , pp. 438-442.
	Fan, Jr-Min, Ruey-Shan Guo, Shi-Chung Chang, and Kian-Huei Lee. 1996. "Abnormal Trend Detection of Sequence-Disordered Data Using EWMA Method." <i>IEEE/SEMI Advanced Semiconductor Manufacturing Conference</i> , pp. 169-174.
	Smith, Taber and Duane Boning. 1996. "A Self-Tuning EWMA Controller Utilizing Artificial Neural Network Function Approximation Techniques." <i>IEEE/CPMT International Electronics Manufacturing Technology Symposium</i> , pp. 355-363.
	Guo, Ruey-Shan, Li-Shia Huang, Argon Chen, and Jin-Jung Chen. October 1997. "A Cost-Effective Methodology for a Run-by-Run EWMA Controller." <i>6<sup>th</sup> International Symposium on Semiconductor Manufacturing</i> , pp. 61-64.
	November 1999. "How to Use EWMA to Achieve SPC and EPC Control." <i>International Symposium on NDT Contribution to the Infrastructure Safety Systems</i> , Tores, Brazil. < <a href="http://www.ndt.net/abstract/ndtiss99/data/35.htm">http://www.ndt.net/abstract/ndtiss99/data/35.htm</a> >
	Chen, Argon and Ruey-Shan Guo. February 2001. "Age-Based Double EWMA Controller and Its Application to CMP Processes." <i>IEEE Transactions on Semiconductor Manufacturing</i> , vol. 14, no. 1, pp. 11-19.
	Wang, LiRen and Hefin Rowlands. 2001. "A Novel NN-Fuzzy-SPC Feedback Control System." <i>8<sup>th</sup> IEEE International Conference on Emerging Technologies and Factory Automation</i> , pp. 417-423.
	Good, Richard and S. Joe Qin. May 2002. "Stability Analysis of Double EWMA Run-to-Run Control with Metrology Delay." <i>IEEE/CPMT International Electronics Manufacturing Technology Symposium</i> , pp. 355-363.
	December 16, 2003. International Search Report for PCT/US03/23964.

EXAMINER

DATE CONSIDERED

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				APPLICANT Alexander T. SCHWARM et al.			
				FILING DATE August 1, 2003		GROUP 2812	
<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	3,205,485	09/07/65	Noltingk			10/21/60	
	3,229,198	01/11/66	Libby			09/28/62	
	3,767,900	10/23/73	Chao et al.			06/23/71	
	3,920,965	11/18/75	Sohrwardy			03/04/74	
	4,000,458	12/28/76	Miller et al.			08/21/75	
	4,207,520	06/10/80	Flora et al.			04/06/78	
	4,209,744	06/24/80	Gerasimov et al.			03/27/78	
	4,302,721	11/24/81	Urbanek et al.			05/15/79	
	4,368,510	01/11/83	Anderson			10/20/80	
	4,609,870	09/02/86	Lale et al.			09/13/84	
	4,616,308	10/07/86	Morshedi et al.			12/02/85	
	4,663,703	05/05/87	Axelby et al.			10/02/85	
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	4,755,753	07/05/88	Chern			07/23/86	
	4,757,259	07/12/88	Charpentier			11/05/86	
	4,796,194	01/03/89	Atherton			08/20/86	
	4,901,218	02/13/90	Cornwell			03/04/88	
	4,938,600	07/03/90	Into			02/09/89	
	4,967,381	10/30/90	Lane et al.			07/06/89	
	5,089,970	02/18/92	Lee et al.			10/05/89	
	5,108,570	04/28/92	Wang			03/30/90	
	5,208,765	05/04/93	Turnbull			07/20/90	
	5,220,517	06/15/93	Sierk et al.			08/31/90	
5,226,118	07/06/93	Baker et al.			01/29/91		
5,231,585	07/27/93	Kobayashi et al.			06/20/90		
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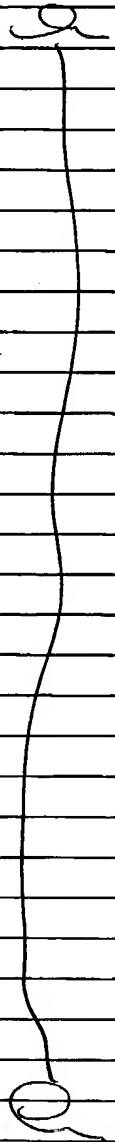

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	5,270,222	12/14/93	Moslehi			12/31/90	
	5,283,141	02/01/94	Yoon et al.			03/05/92	
	5,295,242	03/15/94	Mashruwala et al.			11/02/90	
	5,309,221	05/03/94	Fischer et al.			12/31/91	
	5,329,463	07/12/94	Sierk et al.			01/13/93	
	5,338,630	08/16/94	Yoon et al.			11/18/93	
	5,347,446	09/13/94	Iino et al.			02/10/92	
	5,367,624	11/22/94	Cooper			06/11/93	
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	5,398,336	03/14/95	Tantry et al.			06/16/93	
	5,402,367	03/28/95	Sullivan et al.			07/19/93	
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	5,526,293	06/11/96	Mozumder et al.			12/17/93	
	5,534,289	07/09/96	Bilder et al.			01/03/95	
	5,541,510	07/30/96	Danielson			04/06/95	
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE		
	5,546,312	08/13/96	Mozumder et al.			02/24/94		
	5,553,195	09/03/96	Meijer			09/29/94		
	5,586,039	12/17/96	Hirsch et al.			02/27/95		
	5,599,423	02/04/97	Parker et al.			06/30/95		
	5,602,492	02/11/97	Cresswell et al.			04/28/94		
	5,603,707	02/18/97	Trombetta et al.			11/28/95		
	5,617,023	04/01/97	Skalski			02/02/95		
	5,627,083	05/06/97	Tounai			05/12/95		
	5,629,216	05/13/97	Wijaranakula et al.			02/27/96		
	5,642,296	06/24/97	Saxena			07/29/93		
	5,646,870	07/08/97	Krivokapic et al.			02/13/95		
	5,649,169	07/15/97	Berezin et al.			06/20/95		
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	5,657,254	08/12/97	Sierk et al.			04/15/96		
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	5,663,797	09/02/97	Sandhu			05/16/96		
	5,664,987	09/09/97	Renteln			09/04/96		
	5,665,199	09/09/97	Sahota et al.			06/23/95		
	5,666,297	09/09/97	Britt et al.			05/13/94		
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	5,694,325	12/02/97	Fukuda et al.			11/22/95		
	5,698,989	12/16/97	Nulman			09/13/96		
	5,719,495	02/17/98	Moslehi			06/05/96		
	5,719,796	02/17/98	Chen			12/04/95		
	5,735,055	04/07/98	Hochbein et al.			04/23/96		
	5,740,429	04/14/98	Wang et al.			07/07/95		
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	5,751,582	05/12/98	Saxena et al.			09/24/96	
	5,754,297	05/19/98	Nulman			04/14/97	
	5,761,064	06/02/98	La et al.			10/06/95	
	5,764,543	06/09/98	Kennedy			06/16/95	
	5,777,901	07/07/98	Berezin et al.			09/29/95	
	5,787,021	07/28/98	Samaha			12/18/95	
	5,787,269	07/28/98	Hyodo			09/19/95	
	5,808,303	09/15/98	Schlagheck et al.			01/29/97	
	5,812,407	09/22/98	Sato et al.			08/12/97	
	5,823,854	10/20/98	Chen			05/28/96	
	5,825,913	10/20/98	Rostami et al.			07/18/95	
	5,828,778	10/27/98	Hagi et al.			07/12/96	
	5,832,224	11/03/98	Fehskens et al.			06/14/96	
	5,838,595	11/17/98	Sullivan et al.			11/25/96	
	5,844,554	12/01/98	Geller et al.			09/17/96	
	5,857,258	01/12/99	Penzes et al.			05/12/94	
	5,859,964	01/12/99	Wang et al.			10/25/96	
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	5,862,054	01/19/99	Li			02/20/97	
	5,863,807	01/26/99	Jang et al.			03/15/96	
	5,867,389	02/02/99	Hamada et al.			11/26/96	
	5,870,306	02/09/99	Harada			06/13/97	
	5,883,437	03/16/99	Maruyama et al.			12/28/95	
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	5,901,313	05/04/99	Wolfe et al.			09/02/97	
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5,910,011	06/08/99	Cruse			05/12/97		
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,912,678	06/15/99	Saxena et al.			04/14/97
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	5,923,553	07/13/99	Yi			10/05/96
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	5,940,300	08/17/99	Ozaki			05/08/97
	5,943,237	08/24/99	Van Boxem			10/17/97
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	5,978,751	11/02/99	Pence et al.			02/25/97
	5,982,920	11/09/99	Tobin, Jr. et al.			01/08/97
	6,002,989	12/14/99	Shiba et al.			04/01/97
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	6,094,688	07/25/00	Mellen-Garnett et al.			03/12/98
	6,097,887	08/01/00	Hardikar et al.			10/27/97
	6,108,092	08/22/00	Sandhu			06/08/99
	6,111,634	08/29/00	Pecen et al.			05/28/97
	6,112,130	08/29/00	Fukuda et al.			10/01/97
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
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	6,128,016	10/03/00	Coelho et al.			12/20/96	
	6,136,163	10/24/00	Cheung et al.			03/05/99	
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	6,148,099	11/14/00	Lee et al.			07/03/97	
	6,148,239	11/14/00	Funk et al.			12/12/97	
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<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)</b>				ATTY. DOCKET NO. 7720/FPS/MMCS/APC		SERIAL NO. 10/632,107		
				APPLICANT Alexander T. SCHWARM et al.				
				FILING DATE August 1, 2003		GROUP 2812		
<b>U.S. PATENT DOCUMENTS</b>								
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE		
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<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS	
	<del>09/363,966</del> 0255874	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium			
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System			
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder			
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers			
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service			
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems			
	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide			
	09/811,667	03/20/01	Yuan et al.	Fault Tolerant and Automated Computer Software Workflow			
	09/927,444	08/13/01	Ward et al.	Dynamic Control of Wafer-Processing Paths in Semiconductor Manufacturing Processes			
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EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS	
	10/084,092	02/28/02	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements			
	10/135,405	05/01/02	Reiss et al.	Integration of Fault Detection with Run-to-Run Control			
	10/135,451	05/01/02	Shanmugasundram et al.	Dynamic Metrology Schemes and Sampling Schemes for Advanced Process Control in Semiconductor Processing			
	10/172,977	06/18/02	Shanmugasundram et al.	Method, System and Medium for Process Control for the Matching of Tools, Chambers and/or Other Semiconductor-Related Entities			
	10/173,108	06/18/02	Shanmugasundram et al.	Integrating Tool, Module, and Fab Level Control			
	10/174,370	06/18/02	Shanmugasundram et al.	Feedback Control of Plasma-Enhanced Chemical Vapor Deposition Processes			
	10/174,377	06/18/02	Schwarm et al.	Feedback Control of Sub-Atmospheric Chemical Vapor Deposition Processes			
	10/377,654	03/04/03	Kokotov et al.	Method, System and Medium for Controlling Manufacturing Process Using Adaptive Models Based on Empirical Data			
	10/393,531	03/21/03	Shanmugasundram et al.	Copper Wiring Module Control			
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<b>FOREIGN PATENT DOCUMENTS</b>							
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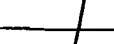


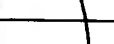
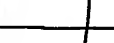

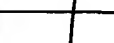
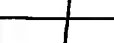
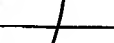


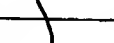
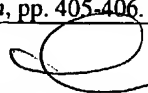
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	WO 01/15865 A1	03/08/01	WO			X	
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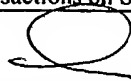



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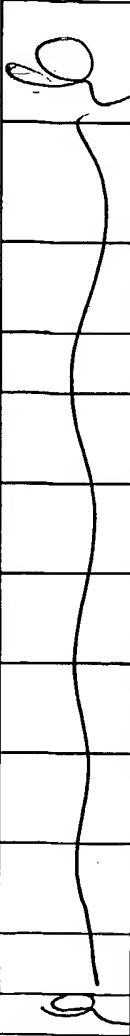

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		<b>FILING DATE</b> August 1, 2003	<b>GROUP</b> 2812
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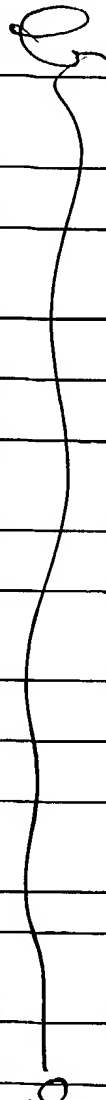

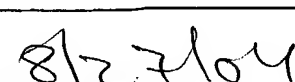
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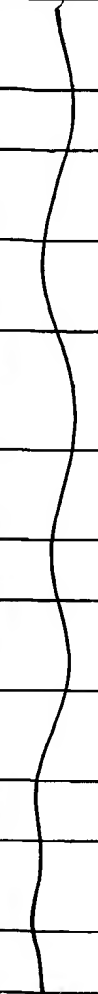


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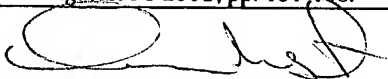
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<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)</b>		<b>ATTY. DOCKET NO.</b> 7720/FPS/MMCS/APC	<b>SERIAL NO.</b> 10/632,107
		<b>APPLICANT</b> Alexander T. SCHWARM et al.	
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<b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b>			
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